

T2100HP

Polymer Thick Film

Description

T2100HP conductor paste is a thermosetting silver filled polymer. This material was designed for die attach and rigid circuit applications.

Key Features

- screen printable
- For die attach and rigid circuit applications



This picture does not show the packaging of T2100HP and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms

Typical Properties

Conductivity	≤.070 Ω/square @ 36 microns cured thickness
Viscosity	250 – 300 Kcps; Brookfield HAT, spindle #14 @ 10 rpm, 25 °C
Coverage	60 cm ² /g
Metal	Ag
Color	Silver

Recommended Processing Guide

Printing Parameters	Polyester Mesh (157 to 230 TPI) Steel Mesh (165 to 325 TPI)
Drying Temperature	150°C
Film Thickness	12 μm, DFT
Paste Compatibility	Compatible with all PriElex products

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Warranty

6 months

Storage

Store at ambient conditions away from direct light. Material should be thoroughly mixed or rolled on a jar roller at a slow speed for 1 hour prior to use

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